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Docket No.: SPLX.P0004

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John Stattler
John Stattler

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Steven Teig, et al.

Serial No.: 09/733,104

Filed: December 7, 2000

For: **Multi-Directional Wiring On A Single Metal Layer**

TECHNOLOGY CENTER 2600
JUN 25 2002

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AMENDMENT AND RESPONSE TO OFFICE ACTION

Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231

Sir:

In response to the Office Action dated January 3, 2002, please amend the patent application as follows:

IN THE CLAIMS:

Please amend claims 1, 3, 7-9, and 14-16 as follows:

1. (Once Amended) An integrated circuit comprising:

Q1